B. Claims

The following is a complete listing of the claims, and replaces all earlier versions and listings.

1. (Currently Amended) An electrode and wiring forming method, comprising:

a step of applying on a substrate a photosensitive resin containing a water-soluble photosensitive resin component and a water-soluble metallic compound;

a step of exposing the applied photosensitive resin;

a step of developing the exposed photosensitive resin to form on the substrate a base pattern containing at least the water-soluble metallic compound;

an absorbing step of absorbing an organic metallic compound containing a metal different from that in the water-soluble metallic compound into the base pattern; and

a baking step of baking the base pattern in which the organic metallic compound is absorbed at a temperature from 400°C to 600°C.

2. (Original) An electrode and wiring forming method according to claim 1, wherein a compounding ratio of the water-soluble metallic compound to the photosensitive resin component is 1.0% by weight to 20% by weight.

3. (Original) An electrode and wiring forming method according to claim 2, wherein the water-soluble metallic compound is a water-soluble metallic compound including rhodium, bismuth, ruthenium, vanadium, chromium, tin, lead, or silicon.

4-10. (Cancelled)

11. (Currently Amended) A method of manufacturing an image-forming apparatus including a plurality of electron-emitting devices and an image-forming member for forming an image by irradiation of electron beams emitted from the electron-emitting devices, comprising:

forming said plurality of electron-emitting devices and said image-forming member,

wherein at least one of an electrode and a wiring is formed by the method comprising:

a step of applying on a substrate a photosensitive resin containing a water-soluble photosensitive resin component and a water-soluble metallic compound;

a step of exposing the applied photosensitive resin;

a step of developing the exposed photosensitive resin to form on the substrate a base pattern containing at least the water-soluble metallic compound;

an absorbing step of absorbing an organic metallic compound containing a metal different from that in the water-soluble metallic compound into the base pattern; and

a baking step of baking the base pattern in which the organic metallic compound is absorbed at a temperature from 400°C to 600°C.

12 (Currently Amended) An electroconductive member forming method, comprising:

a step of forming on a substrate a precursor pattern of the electroconductive member containing at least a metallic compound;

a step of absorbing an organic metallic compound containing a metal different from that in the metallic compound into the precursor pattern; and

a step of baking the precursor pattern that absorbed the organic metallic compound.

13. (Currently Amended) An electrode and wiring forming method, comprising:

a step of forming on a substrate a precursor pattern of the electrode and wiring containing at least a metallic compound;

a step of absorbing an organic metallic compound containing a metal different from that in the metallic compound into the precursor pattern; and

a step of baking the precursor pattern that absorbed the organic metallic compound to form the electrode and wiring.

14-17. (Cancelled)

18. (New) The method according to claim 11, wherein a compounding ratio of the water-soluble metallic compound to the photosensitive resin component is 1.0% by weight to 20% by weight.

19. (New) The method according to claim 18, wherein the water-soluble metallic compound is a water-soluble metallic compound including rhodium, bismuth, ruthenium, vanadium, chromium, tin, lead, or silicon.

20. (New) The method according to claim 12, wherein a compounding ratio of the water-soluble metallic compound to the photosensitive resin component is 1.0% by weight to 20% by weight.

21. (New) The method according to claim 20, wherein the water-soluble metallic compound is a water-soluble metallic compound including rhodium, bismuth, ruthenium, vanadium, chromium, tin, lead, or silicon.

22. (New) The method according to claim 13, wherein a compounding ratio of the water-soluble metallic compound to the photosensitive resin component is 1.0% by weight to 20% by weight.

23. (New) The method according to claim 22, wherein the water-soluble metallic compound is a water-soluble metallic compound including rhodium, bismuth, ruthenium, vanadium, chromium, tin, lead, or silicon.